

Submitted herewith for filing is the Patent Application of:

Inventor: MOU-SHIUNG LIN

For: WAFER SCALE PACKAGING SCHEME

Enclosed are:

- ☒ 6 sheets of formal drawing(s).
☐ An assignment of the invention to
☐ An associate power of attorney
☒ Small Entity Status

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$395
TOTAL CLAIMS	36 -20=	16	x 11.=	\$176.
INDEP CLAIMS	5 -3=	2	x 41.=	\$82.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$653.
			ASSIGNMENT	
			TOTAL	\$653.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 653. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,
George D. Saile
GEORGE D. SAILE, REG. NO. 19,572